

**We claim:**

1. A mold comprising two mold halves, one of the mold halves comprising a contact section which is adapted to contact a surface of a semiconductor chip mounted in the mold, in use.
- 5 2. A mold according to claim 1, wherein the contact section of the mold which is adapted to engage with the surface of the semiconductor chip, is in the form of a removable member which is mounted on one of the mold halves.
- 10 3. A mold according to claim 2, wherein the removable member is mounted for movement relative to the mold half on which it is mounted.
4. A mold according to claim 3, further comprising biasing means to bias the member into a mold cavity defined by the mold halves.
- 15 5. A mold according to claim 1, wherein the contact section comprises a compressible material.
6. A mold according to claim 1, wherein a surface of the contact section, which is adapted to contact the surface of a semiconductor chip in use, is profiled to minimise seepage of molding material between the section of the mold and the surface of the semiconductor chip during molding.
- 20 7. A method of molding material around a semiconductor chip, the method comprising mounting a semiconductor chip on a substrate, inserting the
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substrate and the semiconductor chip into a mold, such that a contact section of the mold contacts a surface of the chip, molding the molding material around the semiconductor chip and the contact section to form a molded package, and subsequently removing the molded package from the mold.

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8. A method according to claim 7, wherein the surface of the chip contacted by the contact section is an active surface of the chip.

9. A method according to claim 7, wherein the surface of the chip contacted

10 by the contact section is a non-active surface of the chip.